



Material Content Data Sheet



Sales Product Name				IKFW50N60ET		Issued		1. August 2018	
MA#				MA001674420					
Package				PG-HSIP247-3-1		Weight*		5792.85 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	2.181	0.04	0.04	376	376	
chip_2	inorganic material	silicon	7440-21-3	5.465	0.09	0.09	943	943	
leadframe	inorganic material	phosphorus	7723-14-0	0.164	0.00		28		
	non noble metal	iron	7439-89-6	0.545	0.01		94		
	non noble metal	copper	7440-50-8	544.561	9.40	9.41	94006	94128	
	non noble metal	aluminium	7429-90-5	15.558	0.27	0.27	2686	2686	
wire	inorganic material	zinc oxide	1314-13-2	0.340	0.01		59		
encapsulation	plastics	silicone resin	-	0.766	0.01		132		
	inorganic material	alumina	1344-28-1	7.405	0.13		1278		
	organic material	carbon black	1333-86-4	21.835	0.38		3769		
	plastics	epoxy resin	-	414.864	7.16		71617		
	inorganic material	silicon dioxide	60676-86-0	1746.797	30.15	37.84	301544	378399	
leadfinish	non noble metal	tin	7440-31-5	16.291	0.28	0.28	2812	2812	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.456	0.01	0.01	79	80	
solder	non noble metal	antimony	7440-36-0	0.553	0.01		96		
	noble metal	silver	7440-22-4	1.383	0.02		239		
	non noble metal	tin	7440-31-5	3.597	0.06	0.09	621	956	
heatspreader	inorganic material	phosphorus	7723-14-0	0.903	0.02		156		
	non noble metal	iron	7439-89-6	3.010	0.05		520		
	non noble metal	copper	7440-50-8	3006.169	51.90	51.97	518944	519620	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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